

L Number	Hits	Search Text	DB	Time stamp
1	54993	204/\$.ccls.	USPAT; EPO; JPO; DERWENT	2002/06/03 10:41
2	48750	electroplat\$3	USPAT; EPO; JPO; DERWENT	2002/06/03 10:41
3	314660	deposition	USPAT; EPO; JPO; DERWENT	2002/06/03 10:42
4	197707	depositing	USPAT; EPO; JPO; DERWENT	2002/06/03 10:42
5	4361	electrochemical same deposition	USPAT; EPO; JPO; DERWENT	2002/06/03 10:42
6	1100	electrochemical same depositing	USPAT; EPO; JPO; DERWENT	2002/06/03 10:42
7	52722	(electrochemical same deposition) (electrochemical same depositing) electroplat\$3	USPAT; EPO; JPO; DERWENT	2002/06/03 10:42
8	3349	((electrochemical same deposition) (electrochemical same depositing) electroplat\$3) and 204/\$.ccls.	USPAT; EPO; JPO; DERWENT	2002/06/03 10:42
9	223	((electrochemical same deposition) (electrochemical same depositing) electroplat\$3) and 204/\$.ccls.) and spin	USPAT; EPO; JPO; DERWENT	2002/06/03 10:42
10	5293	thermal same anneal	USPAT; EPO; JPO; DERWENT	2002/06/03 10:43
11	822244	cells or chambers	USPAT; EPO; JPO; DERWENT	2002/06/03 10:43
12	6	(thermal same anneal) and (((electrochemical same deposition) (electrochemical same depositing) electroplat\$3) and 204/\$.ccls.) and spin	USPAT; EPO; JPO; DERWENT	2002/06/03 10:43
13	6	((thermal same anneal) and (((electrochemical same deposition) (electrochemical same depositing) electroplat\$3) and 204/\$.ccls.) and spin)) and (((electrochemical same deposition) (electrochemical same depositing) electroplat\$3) and 204/\$.ccls.)	USPAT; EPO; JPO; DERWENT	2002/06/03 10:44
14	1143	(thermal same anneal) and (cells or chambers)	USPAT; EPO; JPO; DERWENT	2002/06/03 10:44
16	5	((thermal same anneal) and (cells or chambers)) and (((electrochemical same deposition) (electrochemical same depositing) electroplat\$3) and 204/\$.ccls.)	USPAT; EPO; JPO; DERWENT	2002/06/03 10:45
15	52	((thermal same anneal) and (cells or chambers)) and ((electrochemical same deposition) (electrochemical same depositing) electroplat\$3)	USPAT; EPO; JPO; DERWENT	2002/06/03 10:46
17	34	((thermal same anneal) and (cells or chambers)) and ((electrochemical same deposition) (electrochemical same depositing) electroplat\$3); and integrated	USPAT; EPO; JPO; DERWENT	2002/06/03 10:47
18	718678	integrated	USPAT; EPO; JPO; DERWENT	2002/06/03 10:47
19	235	204/\$.ccls. and ((electrochemical same deposition) (electrochemical same depositing) electroplat\$3) and integrated and (cells or chambers)	USPAT; EPO; JPO; DERWENT	2002/06/03 10:48

20	1502000	wafer or substrate	USPAT; EPO; JPO; DERWENT	2002/06/03 10:50
21	191	(wafer or substrate) and (204/\$.ccls. and ((electrochemical same deposition) (electrochemical same depositing) electroplat\$3) and integrated and (cells or chambers))	USPAT; EPO; JPO; DERWENT	2002/06/03 10:51
22	5660	transfer same robot	USPAT; EPO; JPO; DERWENT	2002/06/03 10:51
23	27776	transfer same arm	USPAT; EPO; JPO; DERWENT	2002/06/03 10:51
24	31590	(transfer same robot) (transfer same arm)	USPAT; EPO; JPO; DERWENT	2002/06/03 10:51
25	19	((transfer same robot) (transfer same arm)) and ((wafer or substrate) and (204/\$.ccls. and ((electrochemical same deposition) (electrochemical same depositing) electroplat\$3) and integrated and (cells or chambers)))	USPAT; EPO; JPO; DERWENT	2002/06/03 10:51

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21	191	(wafer or substrate) and (204/\$.ccls. and ((electrochemical same deposition) (electrochemical same depositing) electroplat\$3) and integrated and (cells or chambers))	USPAT; EPO; JPO; DERWENT	2002/06/03 10:51
22	5660	transfer same robot	USPAT; EPO; JPO; DERWENT	2002/06/03 10:51
23	27776	transfer same arm	USPAT; EPO; JPO; DERWENT	2002/06/03 10:51
24	31590	(transfer same robot) (transfer same arm)	USPAT; EPO; JPO; DERWENT	2002/06/03 10:51
25	19	((transfer same robot) (transfer same arm)) and ((wafer or substrate) and (204/\$.ccls. and ((electrochemical same deposition) (electrochemical same depositing) electroplat\$3) and integrated and (cells or chambers)))	USPAT; EPO; JPO; DERWENT	2002/06/03 12:07
26	121	((electrochemical same deposition) (electrochemical same depositing) electroplat\$3) and 204/\$.ccls.) and rinse and dry	USPAT; EPO; JPO; DERWENT	2002/06/03 12:08
27	55927	replenish\$3	USPAT; EPO; JPO; DERWENT	2002/06/03 12:08
28	73577	recycle	USPAT; EPO; JPO; DERWENT	2002/06/03 12:08
29	55275	recirculation	USPAT; EPO; JPO; DERWENT	2002/06/03 12:08
30	177129	replenish\$3 recycle recirculation	USPAT; EPO; JPO; DERWENT	2002/06/03 12:08
31	52	(replenish\$3 recycle recirculation) and (((electrochemical same deposition) (electrochemical same depositing) electroplat\$3) and 204/\$.ccls.) and rinse and dry)	USPAT; EPO; JPO; DERWENT	2002/06/03 12:08
32	26	((replenish\$3 recycle recirculation) and (((electrochemical same deposition) (electrochemical same depositing) electroplat\$3) and 204/\$.ccls.) and rinse and dry)) and filter	USPAT; EPO; JPO; DERWENT	2002/06/03 12:08
33	784940	analy\$4	USPAT; EPO; JPO; DERWENT	2002/06/03 12:09
34	265224	chemical and analy\$4	USPAT; EPO; JPO; DERWENT	2002/06/03 12:09
35	13	(chemical and analy\$4) and (((replenish\$3 recycle recirculation) and (((electrochemical same deposition) (electrochemical same depositing) electroplat\$3) and 204/\$.ccls.) and rinse and dry)) and filter)	USPAT; EPO; JPO; DERWENT	2002/06/03 13:30
36	21	"spin-rinse-dry"	USPAT; EPO; JPO; DERWENT	2002/06/03 13:31
37	5	"spin-rinse-dry" and 204/\$.ccls.	USPAT; EPO; JPO; DERWENT	2002/06/03 13:30
38	9	"spin-rinse-dry" and ((electrochemical same deposition) (electrochemical same depositing) electroplat\$3)	USPAT; EPO; JPO; DERWENT	2002/06/03 13:31

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